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FDBL0260N100

N-Channel PowerTrench[®] MOSFET 100 V, 200 A, 2.6 m Ω

- Max $R_{DS(on)}$ = 2.6 m Ω at V_{GS} = 10 V, I_D = 80 A
- Max $Q_{g(tot)}$ = 116 nC at V_{GS} = 10 V, I_D = 80 A
- UIS Capability
- RoHS Compliant

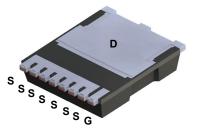
Applications

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch

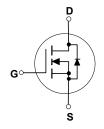




TOP



BOTTOM



MO-299A

MOSFET Maximum Ratings T_C = 25 °C unless otherwise noted.

Symbol	Paramete	er		Ratings	Units	
V_{DS}	Drain to Source Voltage			100	V	
V_{GS}	Gate to Source Voltage			±20	V	
	Drain Current -Continuous	T _C = 25°C	(Note 5)	200		
I_D	-Continuous	T _C = 100°C	(Note 5)	140	Α	
	-Pulsed		(Note 4)	1000		
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	866	mJ	
В	Power Dissipation	T _C = 25°C		250	W	
P_{D}	Power Dissipation	T _A = 25°C	(Note 1a)	3.5	VV	
T _J , T _{STG}	Operating and Storage Junction Temperatu	re Range		-55 to +175	°C	

Thermal Characteristics

$R_{ heta JC}$	Thermal Resistance, Junction to Case	(Note 1)	0.6	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	43	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDBL0260N100	FDBL0260N100	MO-299A	-	-	-

Electrical Characteristics T_J = 25 °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Chara	icteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25 °C		53		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 80 V, V _{GS} = 0 V			1	μА
I_{GSS}	Gate to Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V			±100	nA

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2	2.7	4	V
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 80 \text{ A}$		2.1	2.6	mΩ
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		-13		mV/°C
9 _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 80 A		170		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V = 50 V V = 0 V	6175	9265	pF
Coss	Output Capacitance	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz	1330	1995	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1011 12	40	60	pF
R_q	Gate Resistance	V _{GS} = 0.5V, f = 1MHz	2.6		Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time				26	42	ns
t _r	Rise Time		V_{DD} = 50 V, I_{D} = 80 A, V_{GS} = 10 V, R_{GEN} = 6 Ω		34	54	ns
t _{d(off)}	Turn-Off Delay Time	V _{GS} = 10 V, R _{GEN}			47	75	ns
t _f	Fall Time				19	34	ns
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0$ to 10 V			83	116	nC
$Q_{g(th)}$	Threshold Gate Charge	V _{GS} = 0 to 2 V	V _{DD} = 50 V,		11	16	nC
Q_{gs}	Gate to Source Gate Charge		I _D = 80 A		28		nC
Q_{gd}	Gate to Drain "Miller" Charge				16		nC

Drain-Source Diode Characteristics

I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	200	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	1000	Α
V	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 80 \text{ A}$ (Note 2)	2)	0.8	1.3	\/
V_{SD}	Source to Drain Diode 1 ofward voltage	$V_{GS} = 0 \text{ V}, I_{S} = 40 \text{ A}$ (Note 2)	2)	0.8	1.2	V
t _{rr}	Reverse Recovery Time	- I _F = 80 A, di/dt = 100 A/μs		71	113	ns
Q _{rr}	Reverse Recovery Charge	I _F = 80 A, αl/αι = 100 A/μs		121	194	nC

- 2. Pulse Test: Pulse Width < 300 μ s, Duty cycle < 2.0 %.
- 3. E_{AS} of 866 mJ is based on starting T_J = 25 °C, L = 0.3 mH, I_{AS} = 76 A, V_{DD} = 90 V, V_{GS} = 10 V. 100% test at L = 0.1 mH, I_{AS} = 110 A.
- 4. Pulsed Id please refer to Figure "Forward Bias Safe Operating Area" for more details.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

^{1.} R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.

a) 43 °C/W when mounted on a 1 in 2 pad of 2 oz copper.

Typical Characteristics $T_J = 25 \, ^{\circ}\text{C}$ unless otherwise noted.

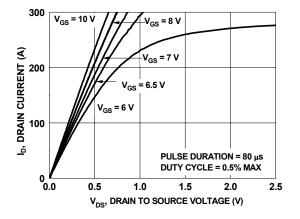


Figure 1. On Region Characteristics

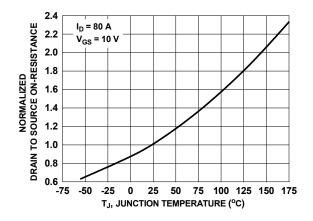


Figure 3. Normalized On Resistance vs. Junction Temperature

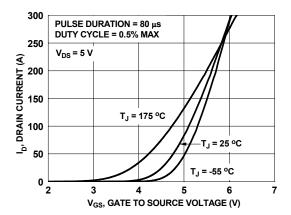


Figure 5. Transfer Characteristics

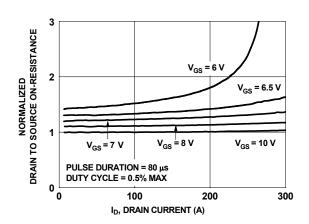


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

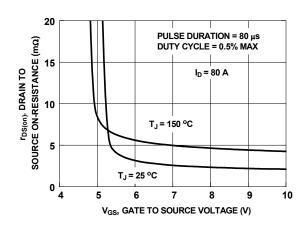


Figure 4. On-Resistance vs. Gate to Source Voltage

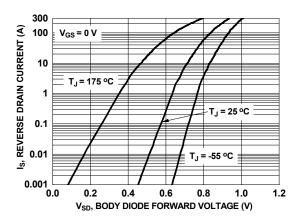


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

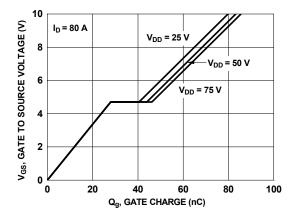


Figure 7. Gate Charge Characteristics

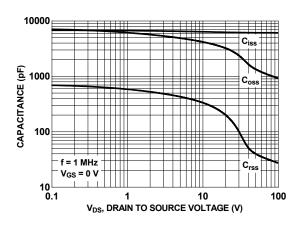


Figure 8. Capacitance vs. Drain to Source Voltage

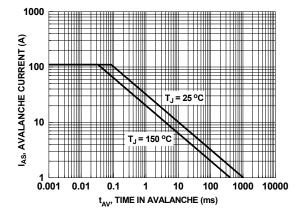


Figure 9. Unclamped Inductive Switching Capability

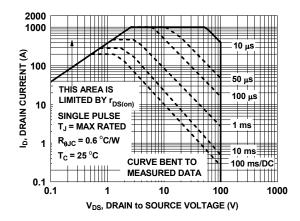


Figure 10. Forward Bias Safe Operating Area

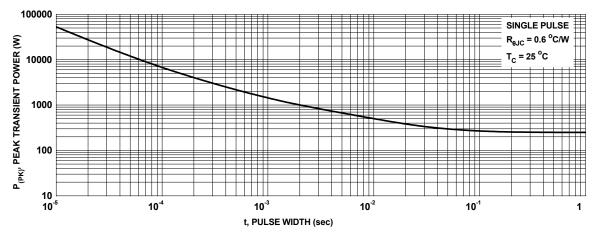


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted.

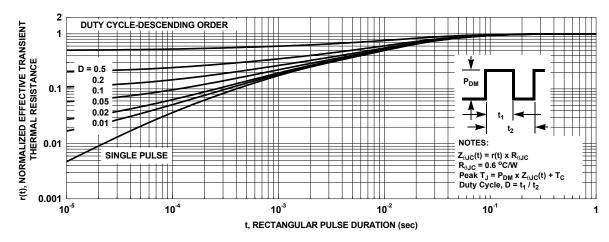
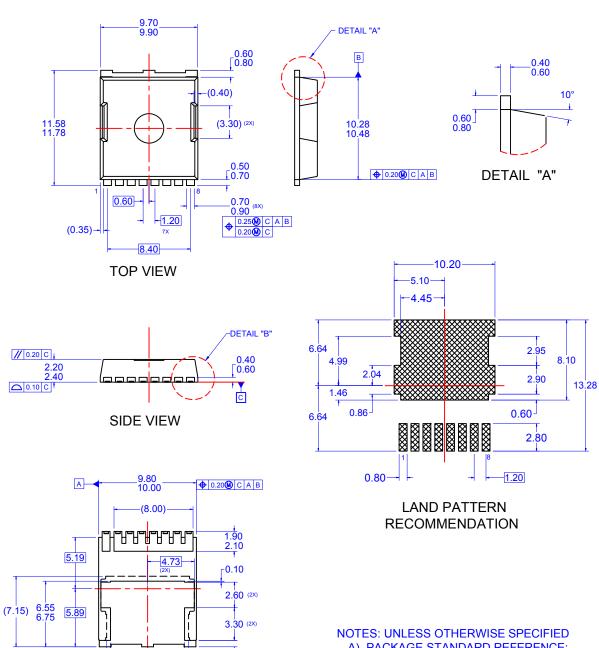
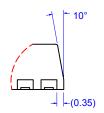


Figure 12. Junction-to-Case Transient Thermal Response Curve



- A) PACKAGE STANDARD REFERENCE: JEDEC MO-299, ISSUE A, DATED NOVEMBER
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: MKT-PSOF08AREV3

- - 1.20 0.65-3.75 7.60 -(8.30) **BOTTOM VIEW**



DETAIL "B"

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